

Data sheet Product ICK S R 50 x 30



Heatsinks and active heatsinks for processors>Pin heatsinks

Ø 50 x 30 mm, pin heatsinks round

Features

design:	round
way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
diameter:	50 mm
height:	30 mm
plate thickness:	3.5 mm
weight:	45.28 g
thermal resistance:	6.1 - 1.1 K/W
dissipation loss:	9.84 W
surface:	Al-natural

Technical Drawing

